Compliant with IEC 62474/ D9.00

MICROCHIP  Semiconductor Device Type: CB (M7X) 003 SOT-23A Matte Tin				Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)			
Semiconductor Device Type:	Г	"Contained In"	% Total	1						e3
Basic Substance	CAS Number	Sub-Component	Weight	mg/part	ppm	9.42	(mg) Total	Mold Compound	% ot Total Weight	63.21
Silica, vitreous	60676-86-0	Mold Compound	53.729	8.006	537,285		Silica, vitreous	60676-86-0	85.00	
Epoxy Resin (No bromine, No diantimony trioxide)	Trade Secret	Mold Compound	3.872	0.577	38,716		Epoxy Resin	Trade Secret	6.13	
Phenolic Resin (No Br / CL SbO3, No diantimony trioxide)	Trade Secret	Mold Compound	3.872	0.577	38,716		Phenolic Resin	Trade Secret	6.13	
Epoxy, Cresol Novolac	29690-82-2	Mold Compound	1.549	0.231	15,486		Epoxy, Cresol Novolac	29690-82-2	2.45	
Carbon Black	1333-86-4	Mold Compound	0.190	0.028	1,896		Carbon Black	1333-86-4	0.30	
Copper	7440-50-8	Lead Frame	27.037	4.029	270,371			Total	100.00	
Iron	7439-89-6	Lead Frame	0.665	0.099	6,651	4.22	(mg) Total	Lead Frame	% of Total Weight	28.3
Silver	7440-22-4	Lead Frame	0.539	0.080	5,391		Copper	7440-50-8	95.54	
Zinc	7440-66-6	Lead Frame	0.035	0.005	354		Iron	7439-89-6	2.35	
Phosphorous	7723-14-0	Lead Frame	0.023	0.003	233		Silver	7440-22-4	1.91	
Metal oxide	Trade Secret	Die Attach	0.845	0.126	8,448		Zinc	7440-66-6	0.13	
Epoxy resins	Trade Secret	Die Attach	0.845	0.126	8,448		Phosphorous	7723-14-0	0.08	
Glycol ethers	Trade Secret	Die Attach	0.640	0.095	6,400			Total	100.00	<b>u</b>
Curing / Hardener	Trade Secret	Die Attach	0.230	0.034	2.304	0.38	(mg) Total	Die Attach	% of Total Weight	2.56
Silicon	7440-21-3	Chip (Die)	3,170	0.472	31,700		Metal oxide	Trade Secret	33.00	1
Gold	7440-57-5	Wire Bond	0.740	0.110	7,400		Epoxy resins	Trade Secret	33.00	
Tin		Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	2.020	0.301	20,200		Glycol ethers	Trade Secret	25.00	
1111	7440 01 0	TOTALS:	100.000	14.900	1.000.000		Curing / Hardener	Trade Secret	9.00	
Material compilation	0.0440	a Total Mass			.,000,000		Curing/ Harderies	Total	100.00	Ш
		g rotal Mass								
s semiconductor device and its homogenous materials comply w		9	8 June 2011) ar	nd 2015/863/EU	(31 March					
	ith EU Directives	9	8 June 2011) ar	nd 2015/863/EU	(31 March	0.47	Total (mg)	Chip (Die)	% of Total Weight	3.17
5) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption	ith EU Directives (zero)	: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (0	8 June 2011) ar	nd 2015/863/EU	(31 March	0.47	,	,		3.17
5) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption mpliance with the above EU Directives has been verified via interi	ith EU Directives (zero) nal design contro	22002/95/EC (27 January 2003) & Directive 2011/65/EU (0) Is, supplier declarations, and /or analytical test data.	·			0.47	Total (mg)  Doped Silicon	Chip (Die) 7440-21-3 Total	% of Total Weight	
) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption pliance with the above EU Directives has been verified via intern hemical substance is absent from the list above, the chemical s porated's knowledge and belief as of the date of this document is not below the threshold of regulatory concern for any regulat ing compounds used by Microchip meet the UL94 V0 flammabil	ith EU Directives (zero) nal design contro ubstance is NOT there is no credi ory scheme work	2: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (0: ls, supplier declarations, and /or analytical test data. an intentional ingredient in the semiconductor device and ble reason to believe that the unavoidable impurity conceid-wide.	I, to the best of intration of the	Microchip Teo	hnology	0.47	,	7440-21-3	100.00	
s semiconductor device and its homogenous materials comply w 5) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption mpliance with the above EU Directives has been verified via interrichemical substance is absent from the list above, the chemical sorporated's knowledge and belief as of the date of this document, is not below the threshold of regulatory concern for any regulated ding compounds used by Microchip meet the UL94 V0 flammabils://ul.com/global/eng/pages/offerings/industries/chemicals/plastic protective "tubes" in which the specific product is shipped are retain "reels" may be made from PVC plastic.	ith EU Directives (zero)  al design contro  ubstance is NOT  there is no credi ory scheme work  ity standard for p  s/	2002/95/EC (27 January 2003) & Directive 2011/65/EU (0) Is, supplier declarations, and for analytical test data. an intentional ingredient in the semiconductor device and lible reason to believe that the unavoidable impurity conceid-wide.	I, to the best of intration of the	Microchip Tec chemical subs report at	hnology tance, if		Doped Silicon	7440-21-3 Total	100.00	
5) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption inpliance with the above EU Directives has been verified via interrichemical substance is absent from the list above, the chemical supporated's knowledge and belief as of the date of this document is not below the threshold of regulatory concern for any regulated ding compounds used by Microchip meet the UL94 V0 flammabils://ul.com/global/eng/pages/offerings/industries/chemicals/plastic.protective "tubes" in which the specific product is shipped are reain "reels" may be made from PVC plastic.  Trochip Technology Incorporated believes the information in this is or original packing materials is true and correct to the best of its knowledge in the protected from disclosure as trade secrets and sided only as estimates of the average weight of these parts and vided only as estimates of the average weight of these parts and	ith EU Directives (zero)  al design contro  ubstance is NOT  there is no credi  rory scheme work  ty standard for p  s/  nade from polyvi  orm concerning  nowledge and be  compiled based  come information  the average weig	: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (0) Is, supplier declarations, and /or analytical test data. an intentional ingredient in the semiconductor device and ble reason to believe that the unavoidable impurity conceid-wide.  Identical declarations of the unavoidable impurity conceiding the	I, to the best of ntration of the to obtain a test old the packing ncorporated's: gy Incorporate vided by raw and raw materi	Microchip Tec chemical subs report at slip on the ou semiconductor d cannot guara taterial supplie	hnology tance, if ter box and devices in ntee the rs. Supplier formation is		Doped Silicon  (mg) Total	7440-21-3 Total Wire Bond	100.00 100.00 % of Total Weight	: 0.74
5) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption in pliance with the above EU Directives has been verified via interrichemical substance is absent from the list above, the chemical supporated's knowledge and belief as of the date of this document, is not below the threshold of regulatory concern for any regulated in the compounds used by Microchip meet the UL94 V0 flammability. If the compounds used by Microchip meet the UL94 V0 flammability. If the compounds used by Microchip meet the UL94 V0 flammability. If the compounds used by Microchip meet the UL94 V0 flammability. If the compounds used by Microchip meet the UL94 V0 flammability. If the compounds used by Microchip meet the UL94 V0 flammability. If the compounds used by Microchip meet the UL94 V0 flammability. If the compounds used to be used	ith EU Directives (zero)  all design contro  ubstance is NOT  there is no credi  ory scheme work  ty standard for p  s/  nade from polyvi  orm concerning  nowledge and be  compiled based  dome information  the average weig  devices (silicon	2002/95/EC (27 January 2003) & Directive 2011/65/EU (0) Is, supplier declarations, and /or analytical test data. an intentional ingredient in the semiconductor device and ible reason to believe that the unavoidable impurity conceld-wide.  Ilastics. You can access the UL iQTM family of databases the unique of the constant of the con	I, to the best of ntration of the to obtain a test old the packing incorporated's gy Incorporated yraw mand raw materiese estimates dution. The exclution of the statement of th	Microchip Tecchemical substreport at slip on the outside semiconductor d cannot guaraterial suppliers. Ir to not include the sive, limited prisive, limited prisives, limited prisives, limited prisives, limited prisive, limited prisives, limited prisives, limited prisive, limited prisives.	hnology tance, if ter box and r devices in ntee the rs. Supplier formation is trace levels		Doped Silicon  (mg) Total	7440-21-3 Total Wire Bond 7440-57-5	100.00 100.00 % of Total Weight	: 0.74
5) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption inpliance with the above EU Directives has been verified via interrichemical substance is absent from the list above, the chemical supporated's knowledge and belief as of the date of this document is not below the threshold of regulatory concern for any regulated ding compounds used by Microchip meet the UL94 V0 flammabilit/lul.com/global/eng/pages/offerings/industries/chemicals/plastic protective "tubes" in which the specific product is shipped are rain "reels" may be made from PVC plastic.  Trochip Technology Incorporated believes the information in this roriginal packing materials is true and correct to the best of its kepleteness and accuracy of data in this form because it has been rimation is often protected from disclosure as trade secrets and syided only as estimates of the average weight of these parts and opants, metals, and non-metal materials contained within silicon crochip Technology Incorporated does not provide any warranty, ranties provided by Microchip Technology Incorporated and its second in the content of the second in the second of the second of the second opants, metals, and non-metal materials contained within silicon trachip Technology Incorporated does not provide any warranty, ranties provided by Microchip Technology Incorporated and its second of the second of the second opants and its second opants.	ith EU Directives (zero) had design contro ubstance is NOT there is no crediory scheme work ity standard for ps s and from polyviorm concerning nowledge and be compiled based in the average weig devices (silicon express or implied ubsidiaries are concerning and the control of	2:002/95/EC (27 January 2003) & Directive 2011/65/EU (0)  Is, supplier declarations, and /or analytical test data.  an intentional ingredient in the semiconductor device and bible reason to believe that the unavoidable impurity conceid-wide.  Ideatics. You can access the UL iQTM family of databases to a substances restricted by RoHS in Microchip Technology In the substances restricted by RoHS in Microchip Technology In the family of the date listed in this form. Microchip Technology on the ranges provided in Material Safety Data Sheets provimay not have been provided by subcontract assemblers in the of anticipated significant toxic metals components. The IC) in the finished parts.  Id, with respect to the information provided in this declarationtained in Microchip's standard terms and conditions of the Declarations and shall not be liable for any damages, dintered in Microchip's and shall not be liable for any damages, dintered in Microchip's standard terms and conditions of the contraction of the provided of the standard terms and conditions of the Declarations and shall not be liable for any damages, dintered in Microchip's standard terms and conditions of the provided in the standard terms and conditions of the provided in the standard terms and conditions of the provided in the standard terms and conditions of the provided in the standard terms and conditions of the provided in the standard terms and conditions of the provided in the standard terms and conditions of the provided in the standard terms and conditions of the provided in the standard terms and conditions of the provided in the standard terms and conditions of the provided in the standard terms and conditions of the provided the provided terms and conditions of the provided the provided the provided the provided the provided the provided to the provided	I, to the best of ntration of the to obtain a test old the packing ncorporated's gy Incorporated by raw mand raw materiese estimates dition. The exclusale. These are irect or indirect	Microchip Tecchemical subside report at a slip on the outside cannot guaraterial supplie on the outside cannot include a sive, limited provided in Market provided in Market consequential subside reprovided in Market provided in Market provid	hnology tance, if ter box and r devices in ntee the rs. Supplier formation is trace levels oduct icrochip's	0.11	Doped Silicon  (mg) Total  Doped Gold	7440-21-3 Total Wire Bond 7440-57-5 Total  Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1	100.00 100.00 % of Total Weigh	: 0.74

Au 2:09 PM : 8/17/2015